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Part Number:

73800-1000

Status:

Active

Overview:

HDM® Backplane Connector System

Description:

HDM® Board-to-Board Midplane Header, Vertical, SMC, Press-Fit, Long Pin, Open End Option, 144 Circuits

Documents:

3D Model

Drawing (PDF)

Product Specification PS-73780-999 (PDF)

Test Summary TS-73670-990 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Series

Application

Component Type

Overview

Product Name

Style

UPC

Backplane Connectors

73800

Midplane

PCB Header

HDM® Backplane Connector System

HDM®

N/A

800755946376

Physical

Circuits (Loaded)

Circuits (maximum)

Color - Resin

Durability (mating cycles max)

First Mate / Last Break

Flammability

Guide to Mating Part

Keying to Mating Part

Material - Plating Mating

Material - Plating Termination

Material - Resin

Net Weight

Number of Columns

Number of Pairs

Number of Rows

Orientation

PC Tail Length

PCB Locator

PCB Retention

PCB Thickness - Recommended

Packaging Type

Pitch - Mating Interface

Pitch - Termination Interface

Plating min - Mating

Plating min - Termination

Polarized to PCB

Stackable

Surface Mount Compatible (SMC)

Temperature Range - Operating

144

144

Black, Natural

250

No

94V-0

No

None

Gold

Gold

High Temperature Thermoplastic

8.289/g

24

Open Pin Field

6

Vertical

11.50mm

No

Yes

4.00mm

Tube

2.00mm

2.00mm

0.762µm

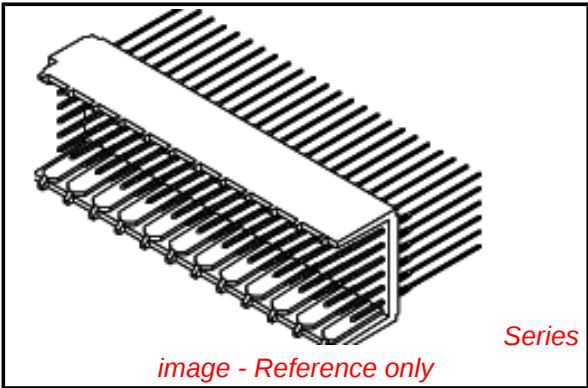
0.051µm

No

Yes

Yes

-55°C to +105°C



EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Low-Halogen Status

Not Reviewed



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

73800Series

Mates With

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description

Product #

Backplane Insertion

Head for 144 Circuits

0622005703

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Product Specification	PS-73780-999
Sales Drawing	SD-73800-001
Test Summary	TS-73670-990

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